

IN THE SPECIFICATION

Pages 1 and 20, below the title, change "Martin Jagle" to "Martin Jaegle";

Page 5, paragraph [0019], change as follows:

[0019] The method is particularly effective if the difference between the thermal expansion coefficient of at least one layer and the thermal expansion coefficient of the substrate is at least $3 * 10^{-6} \text{ K}^{-1}$, in particular at least 10^{-5} K^{-1} (for deposition temperatures in the range of 200°C to 400°C; for higher deposition temperatures even smaller differences of the lateral thermal expansion result in measurable stresses). There is an increased risk of mechanical strain at these orders of magnitude.

Page 5, paragraph [0022], change as follows:

[0022] It is particularly advantageous if at least one semiconductor component composed of two substrates is used. This is advantageous for a Peltier element and/or a thermogenerator element, produced e.g. in a sandwich design. For such microelectromechanical devices, it is advantageous if the thermoelectric layer has a proportion of typical thermoelectric compounds, in particular Bi₂Te₃-related, PbTe-related, SiGe-related and/or skutterudite-type compounds.

Page 11, paragraph [0054], delete "6" as follows:

[0054] The effect of this structuring is manifested in the reduction of the lateral stress (tensile stress, compressive stress)-6, thereby significantly reducing a curvature of the substrate 10 (wafer curvature). Such

wafers are more readily accessible to a postprocessing particularly in photolithographic processors.

Page 12, paragraph [0057], delete "2" as follows:

[0057] Figure 4 illustrates a diagrammatic reproduction of a microscopic representation of a wafer substrate-2 with areas for electrode metal 5. The electrode metal areas 5 are separated by the above-described stress reduction means 2. The electrode metal 5 within the rectangular areas is crack-free since no or only very small mechanical stresses occur within said areas due to the stress reduction means 2. Outside these electrode areas 5, and only outside, cracks 12 are discernible.

Page 15, 8th line, delete "6 Stress direction (lateral stress)".